

# Call for Papers

## iMAPS New England – 44<sup>th</sup> Symposium & Expo

The Largest New England Symposium Dedicated to  
Microelectronics and Packaging

3 Awards - \$500, \$300, \$200 for  
Best Student Papers / Posters



### May 2<sup>nd</sup>, 2017

Holiday Inn – Boxborough Woods Conference Center, Boxborough, Massachusetts

The New England Chapter Symposium Technical Program Committee seeks papers that demonstrate how new technologies and applications are expanding and redefining microelectronics. Areas of interests include:

Industry	Advanced Processes & Materials
<ul style="list-style-type: none"><li>• Biomedical Electronics</li><li>• Telecom - Microwave</li><li>• Military Electronics</li><li>• Consumer Electronics</li><li>• Renewable Energy: Fuel Cells, Solar, Wind</li><li>• Thermal Management</li><li>• Manufacturing, Outsourcing &amp; Quality</li><li>• Solar/PV</li><li>• High Performance Interconnects and Boards</li><li>• Imaging Sensors</li><li>• Emerging Technologies</li></ul>	<ul style="list-style-type: none"><li>• 2.5 / 3D and High Density Packaging</li><li>• Photonic / Optoelectronic Packaging</li><li>• LED Packaging</li><li>• MEMS and Nano Packaging</li><li>• Underfill, Encapsulants, and Adhesives</li><li>• Green Packaging / Compliance with RoHS</li><li>• Flip-Chip and Bumping: Processes, Reliability</li><li>• Wirebonding and Stud Bumping</li><li>• Embedded and Integrated Passives</li><li>• Ceramic, Polymer and Conductive Materials</li><li>• Conformal Electronic Materials</li><li>• Wearable / Printed Electronics</li></ul>

Please send 250 word abstract to [Jon Medernach – Jon.Medernach@mrsisystems.com](mailto:Jon.Medernach@mrsisystems.com)  
Or Send to: [Abstracts@imapsne.org](mailto:Abstracts@imapsne.org)

Submission form and more details available at - [www.imapsne.org](http://www.imapsne.org)

Deadline for Abstract Submission – December 31, 2016